United Resin Corporation

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UNITED RESIN CORPORATION

IS PLEASED TO INTRODUCE ITS

SMT, COB AND HIGH STRENGTH ADHESIVES

CIRCUIT BOND Is a fast, one-component, heat cured SMT adhesive for bonding surface mounted devices to circuit boards. Specially formulated for low ionic contamination, low moisture absorption and heat cure at 178°F. Available in 4 convienent viscosities for your individual needs.

CHIP ON BOARD ADHESIVES:

- **EPOXY DAM CONTROL**
- **EPOXY FILL SYSTEM**
- **HIGH PROFILE GLOP TOP**
- **LOW PROFILE GLOP TOP**

These COB systems combine high purity, low stress and low chloride content for use in the semiconductor industry.

HIGH STRENGTH TOUGH BOND Is a room temperature cure for hard to bond substrates. It is a versatile adhesive which posseses very high tensile and lap shear strengths. Perfect for those applications that you want an item to remain attached.